

# ABSTRACT

of The Disclosure

The invention relates to <sup>^</sup>  
~~used in the technical field of plasma treatment of planar~~  
 elements such as plates, sheets and wafers in electronics and  
 electrical engineering, <sup>and</sup> ~~the invention~~ in essence is a device for  
 treating wafers with a plasma jet. The device comprises the  
 following elements mounted in a closed chamber (1): a drive  
 (12) <sup>that</sup> ~~which~~ effects angular displacement of the holders (14)  
 which are provided with a common rotary drive (18); a plasma  
 jet generator (10); and, mounted outside the closed chamber  
 (1), a manipulator (27) and storage devices (28) for the wafers  
 (29). The wafer (29) to be treated is picked up by the  
 manipulator (27) from the storage device (28) and placed in the  
 holder (14) which together with the wafer (29) passes over the  
 plasma jet generator (10) used for the treatment. The cycle  
 may be repeated a predetermined number of times.

1 Claim, 5 Drawing Figures